2SC3934

Silicon NPN epitaxial planar type

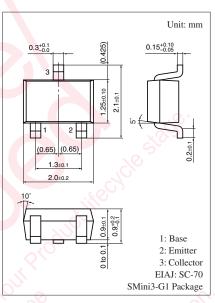
For high-frequency wide-band low-noise amplification

Features

- High transition frequency f_T
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	15	V
Collector-emitter voltage (Base open)	V _{CEO}	12	v
Emitter-base voltage (Collector open)	V _{EBO}	2.5	V
Collector current	I _C	30	mA
Peak collector current	I _{CP}	50	mA
Collector power dissipation	P _C	150	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: 1U

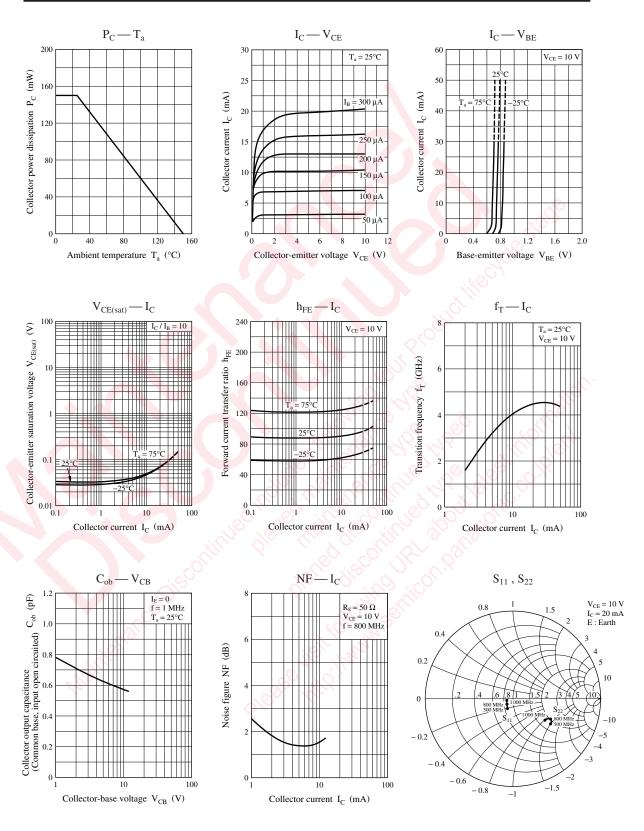
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$	<i>x</i> 2	S	100	nA
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 2 V, I_C = 0$	- A		1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 10 \text{ mA}$	40			
Transition frequency	f _T	$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}, f = 0.8 \text{ GHz}$		4.5		GHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			1.2	pF
Forward transfer gain	$ S_{21e} ^2$	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 20 \text{ mA}, \text{ f} = 0.8 \text{ GHz}$	9	12		dB
Maximum unilateral power gain	G _{UM}	$V_{CE} = 10 \text{ V}, I_C = 20 \text{ mA}, f = 0.8 \text{ GHz}$	12	14		dB
Noise figure	NF	$V_{CE} = 10 \text{ V}, I_C = 5 \text{ mA}, f = 0.8 \text{ GHz}$		1.3	2.5	dB

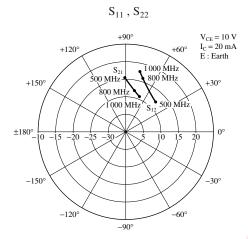
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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